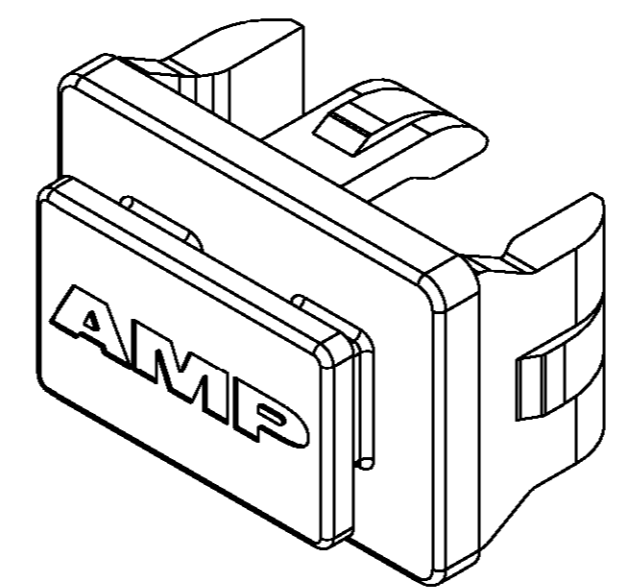
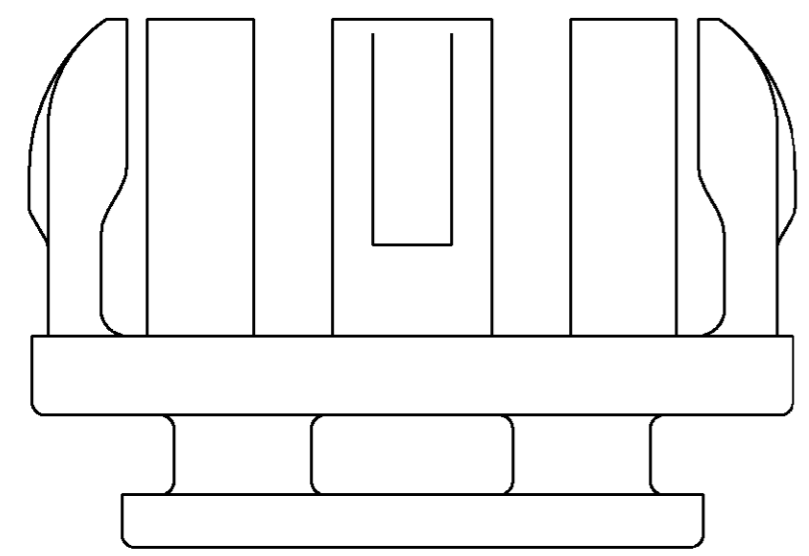


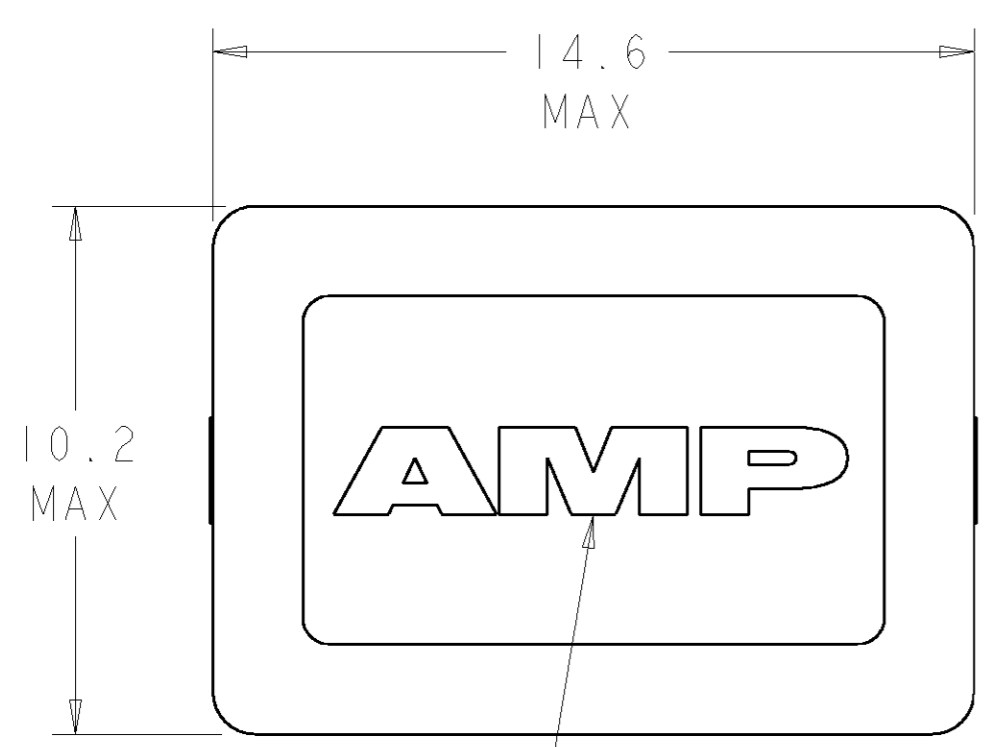
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LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
GP	00						
		O		RLSE PER EC 0UID-0250-00	09OCT2000	DB	RF
		A		REV PER EC 0UID-0277-00	09NOV2000	DB	RF
		B		OBS -2 PER EC 0UID-0289-00	06FEB2001	DB	JK
		C		REVISED PER EC 0S13-0065-01	12NOV01	JG	JK

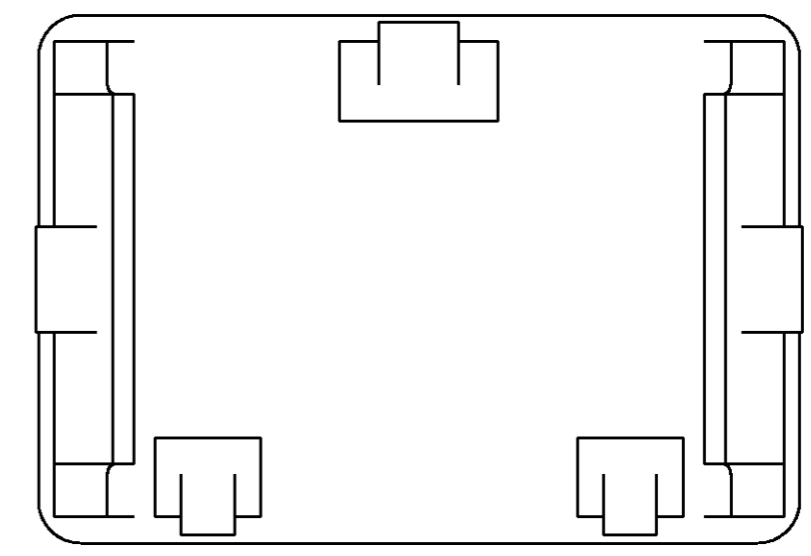
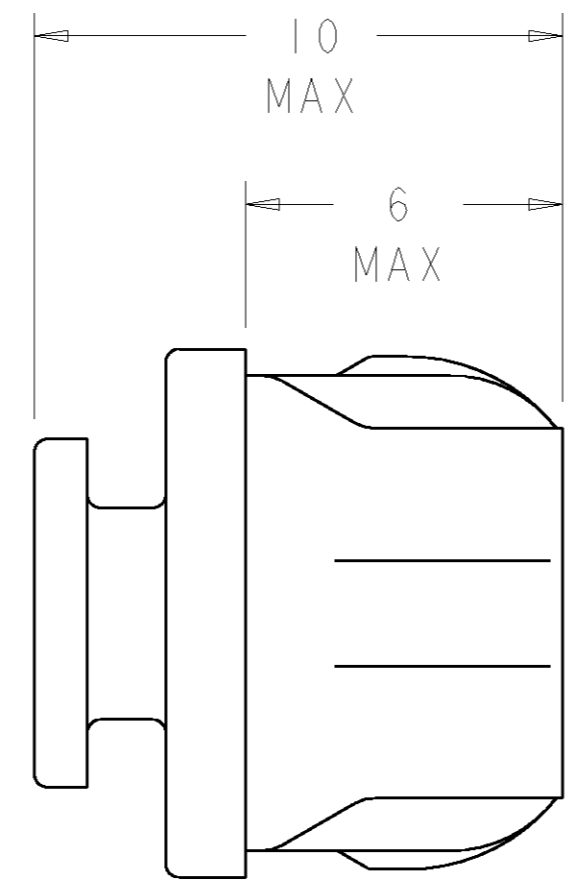


SCALE 5:1

- ① THERMOPLASTIC MOLDING COMPOUND.
- ② TIN PLATING OVER COPPER PLATING.
- ③ OBSOLETE.



AMP LOGO FOR -1 & -2



NO	-	①	1367147-3
YES	②	1367147-1	③ 1367147-2
YES	-	①	1367147-1
AMP LOGO	FINISH	MATERIAL	PART NUMBER

<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.</small>		DWN P. KERLIN 30AUG2000 CHK E. BRIGHT 30AUG2000 APVD E. BRIGHT 30AUG2000	Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm 		PRODUCT SPEC - APPLICATION SPEC - WEIGHT -	NAME COVER, SFP SIZE A2 CAGE CODE 00779 DRAWING NO. 1367147 RESTRICTED TO -
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ± FINISH SEE TABLE		CUSTOMER DRAWING	SCALE 7:1 SHEET 1 OF 1 REV C